

SOT1465-1

wafer level chip-scale package, 31 bumps

26 April 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP31
Package type industry code	WLCSP31
Package style descriptive code	WLCSP (wafer level chip-size package)
Package style suffix code	NA (not applicable)
Mounting method type	S (surface mount)
Issue date	26-4-2016

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.69	-	3.72	3.75	mm
E	package width	2.76	-	2.79	2.82	mm
A	seated height	0.37	-	0.41	0.45	mm
A ₂	package height	0.28	-	0.305	0.33	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	31	-	



2. Package outline

WLCSP31: wafer level chip-scale package, 31 bumps; 2.79 x 3.72 x 0.41 mm (backside coating included) SOT1465-1

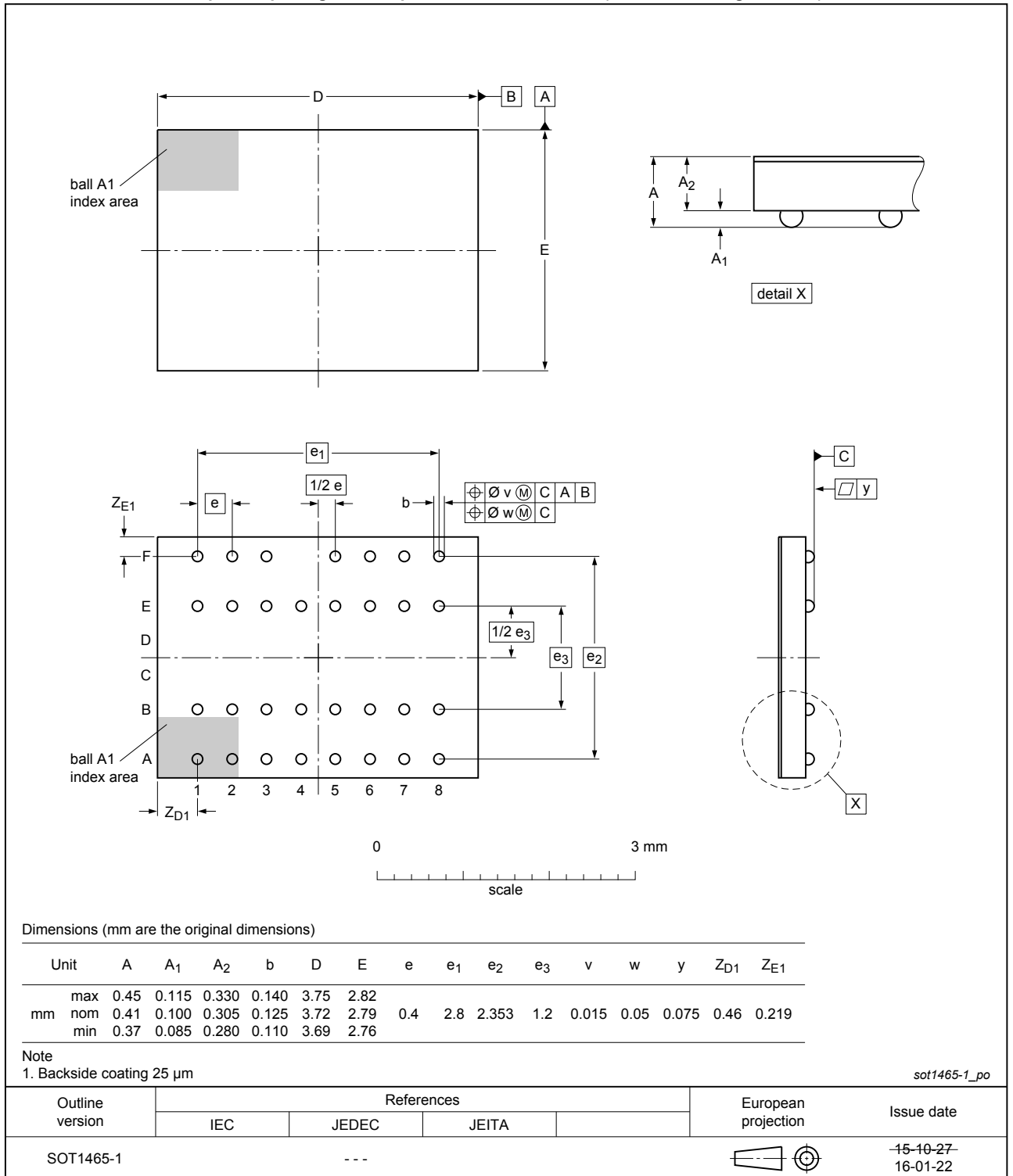


Fig. 1. Package outline WLCSP31 (SOT1465-1)

3. Legal information

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